

Electron Beam Diagnostics for the European XFEL

D. Nölle on behalf of the XFEL Team



XFEL The European XFEL





DIPAC, Basel, 260.05.2009 D. Nölle, DESY







Connection to 2nd stage upgrade included in beam distribution layout **Bunch Compressor** Injector 🐩 Main Linac Collimation 0 Beam Distribution 500 1000 1500 Undulators -1002000 -50 2500 0 3000 Length [m] 50 3500

One injector initially installed

- 17.5 GeV superconducting LINAC
- RF photoinjector, two bunch compression stages
- 3 SASE undulators plus 1 spontaneous source, extension possible
- 5 experimental stations
- potential extension with a second experimental hall



EuropeanXFELE-XFELProperties

- X-ray FEL radiation (0.2 12.4 keV)
 - ultrashort pulse duration <100 fs (rms)</p>
 - extreme pulse intensities 10¹²-10¹⁴ ph
 - coherent radiation x10⁹
 - average brilliance x10⁴
 - Spontaneous radiation (20-100 keV)
 - ultrashort pulse duration <100 fs (rms)











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Not needed bunches can be knocked out to the dump

E



XFEL XFEL-Milestones





■Oct 2002: XFEL supplement to TESLA TDR
 ■Feb 2003: approval by German government as European project with at least 40% funding contributions from partners
 ■July 2006: completion of XFEL TDR, submitted to and approved by International Steering Committee
 ■June 2007: Official project start announced on basis of initially de-scoped start version at 850M€/y2005 construction cost

November 2008: Contracts for the construction of the underground buildings (tunnels, shafts, halls) awarded
 Early 2009: Start of construction. Duration: 5.5 years

2009: Involved countries sign international state treaty which provides the basis for the foundation of the European XFEL GmbH in charge of the construction and operation of the XFEL facility. The research centre will be coordinated and financed on the European level.

DESY coordinates the accelerator consortium.

2014: Start of commissioning





... there is really something happening ...







European



Civil Construction

- Start in Jan 09
- 3 Sites

- DESY
- Osdorfer Born (Switchyard)
- Schenefeld (Exp. Hall)







10

Disclaimer: This talk is not about the special, thrilling stuff! But will cover the large systems of bread and butter diagnostics.

BPM

- Cold
- Warm Cavity
- Electronics Concept
- Beam Size Measurements
 - OTR
- Charge and Transmission
- Machine Protection and Beam Loss Monitoring







ВРМ Туре	Number	Diameter	Single Bunch Resolution
Standard Button BPM	228	40 mm	50 µm
"cold" BPM (Button, 30% Re-entrant Cavity)	104	78 mm	50 µm
Precision BPM (Cavity)	117	10 mm	1 µm
Precision BPM (Cavity)	12	40 mm	1 µm

Collaboration between PSI, CEA and DESY

PSI will provide Electronics, except RF front-end of the Reentrant Cavity BPM
 DESY will provide Mechanics, except Reentrant Cavity BPM
 CEA will provide Reentrant Cavity BPM, incl. RF front-end





Cavity & Button BPM Electronics (PSI Designs)

Undulator RFFE

- 3.3GHz (cavity BPM)
- IQ demodulation
- Requirements: Sub m resolution & drift



ADC Mezzanine

- Six 16-bit ADCs
- 160Msps



FPGA Carrier Board

- Virtex-5 FPGAs
- Flexible interfaces: 1-5Gbit Rocket IO, VME, VXS, Ethernet
- Two mezzanines: 500-pin connectors

Low-cost version of IBFB carrier board (no DSPs, ...), used for all E-XFEL BPMs



Modular BPM Unit

Crate: customized power, backplane & cooling: low noise, high temp. stability



Intra-Bunchtrain Feedback (PSI Contribution)







Bunch Compressor

1000

Injector 👫

500

Ultrafast FPGA-based

bunch-by-bunch feedback

0

Low-Latency BPM & Signal Processing Electronics



High-BW Stripline Kicker Magnets & Power Amps

by Courtesy of B. Keil, PSI

PAUL SCHERRER INSTITUT



DIPAC, Basel, 260.05.2009 D. Nölle, DESY 20 mm button

Cold Reentrant Cavity BPM



- 30 reentrant cavity BPMs will be installed in XFEL cryomodules
- saclay Feedthroughs passed cryogenic tests
 - Cavity has an effective cleaning
- Signal processing electronics uses a single stage down conversion
- RF front-end electronics based on an Printed Circuit board
- Digital electronics designed by PSI







XFEL Cavity BPMs







- Cavity BPMs with 3.3 GHz and Q about 70
- Single Bunch Measurements with 5 MHz Rep Rate
- Goal: 1 µm Resolution, low Drift (0.1 µm/Train)
- Stainless Steel Design based on Shintake's Work
- Two Types
 - 10 mm beam-pipe: Undulator
 - Prototypes ready, good agreement bet. Simulation and Measurement
 - Test in FLASH ongoing
 - 40.5 mm beam-pipe: Warm Beamlines/Feedback
 - Ordering of Prototypes currently prepared





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- OTR out coupling under 45 deg.
- camera tilted by 22.5 deg. to use "Scheimpflug's principle to extend depth of field
- 1:1 reproduction scale
- Resolution requirement 10 30 μm (depending on section)
- Wire scanner ports for optional wire scanners
- Prototype test at FLASH scheduled
- Collaboration with IHEP, Protvino



XFEL Charge and Transmission Monitoring









- Need to control charge and transmission along the LINAC
- Loss monitors show "Zero Losses" when they are broken
 -> need transmission monitoring to make them save.
- Charge monitors (about 30)
 - at the gun
 - at entry and exit of each (warm) Section
 - at each branching point
- Monitor hardware: Reuse of FLASH or DESY type
- Readout: Go for a digital system fast ADC on µTCA
- Online FPGA processing and fast links to neighbor monitors will produce alarms for the machine protection system.

Prototype of an AMC Carrier Board and a 100 MHz ADC/DAC Board

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XFEL Machine Protection System



- Based on FLASH experience
- Distributed system
 - 100 nodes
 - 2 masters
 - Two "off buttons"
 - Laser
 - Dump kicker in distr. system
- Collecting fast and slow inputs
- Check machine integrity before RF pulse
- Cut bunch train in case of fast alarms
- Reaction time < 10 µs
- Based on digital electronics
 - Flexible
 - Customizable



20







- Good experience with FLASH system
- Stay with plastic scintillators and photomultipliers
- about 250 channels distributed over the entire machine
- Reengineering of the FLASH system
 - go to a pure digital readout and FPGA processing
 - AMC, µTCA form factor
- Collaboration with IHEP, Protvino







E-XFEL has entered the construction phase

- even if the International Company is not founded till today
- Collaborations for E-XFEL diagnostics are established
 - even if formal contracts have to wait
- Conceptual designs for the main diagnostic systems are ready
- First prototypes are available or under construction
- Tests at FLASH going on







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